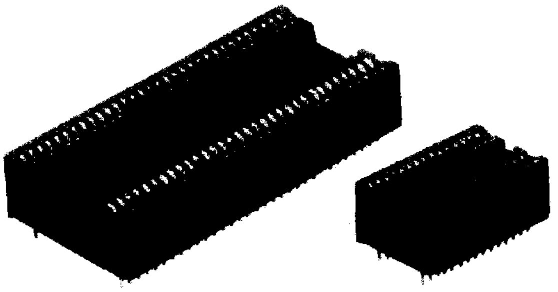
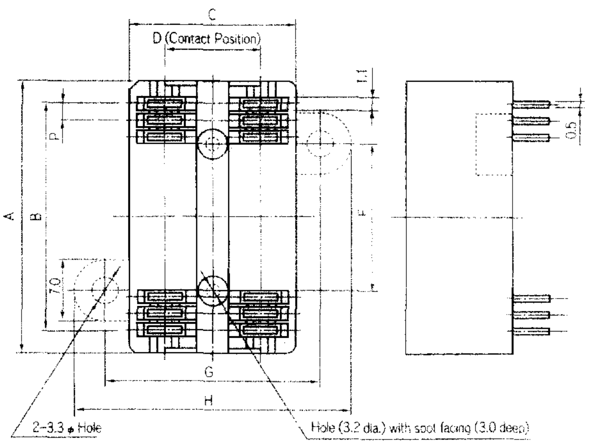
IC 59 SERIES SDIP(Shrink 1.778mm pitch)



●Outline Dimensions



FEATURES

- Shrink pitch (1.778mm) sockets for high-density mounting.
- Dual wipe contact ensures high reliability.
- A piggy-back design allows replacement of the top socket without desoldering.

SPECIFICATIONS

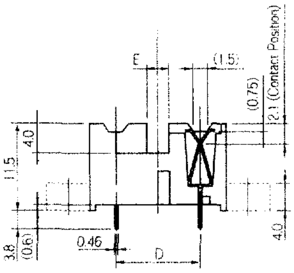
PERFORMANCE

Insulation Resistance	1,000MΩ min. at 500VDC
Dielectric Withstanding Voltage	1,000VAC rms for 1 minute
Contact Resistance	20mΩ max. at 10mA
Current Rating	1A
Operating Temperature Range	170℃ max. continuous

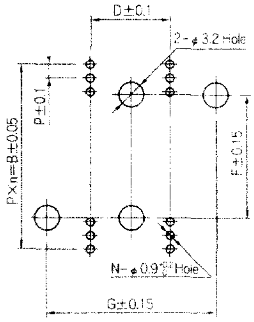
MATERIAL AND FINISH

Housing	PPS (glass-filled), UL94V-0 rated
Contacts	Copper alloy, gold plating over nickel

●Detail of Contact



●Recommended PC Board Patterns (TOP VIEW)



ORDERING CODE

IC59—4806—G4MF

MF = With
Flange option: Unmarked = Without
Straight solder dip terminal
Type of contact plating G = Gold
Distance between IC terminal rows: 6 = 0.6 inches
Number of leads
IC59 series

Part No.	No. of Leads	P	A	B	C	D	E	F	G	H	Center Mounting Hole
IC59—1403—G4 (MF)	14	1.778	14.5	10.668	15.0	7.80	—	6.0	21.0	28.0	—
IC59—1803—G4 (MF)	18	1.778	18.5	14.224	15.0	7.80	—	8.0	21.0	28.0	—
IC59—2203—G4 (MF)	22	1.778	22.0	17.78	15.0	7.80	—	11.0	21.0	28.0	—
IC59—2403—G4 (MF)	24	1.778	24.0	19.556	15.0	7.80	2.0	12.0	21.0	28.0	—
IC59—3004—G4 (MF)	30	1.780	29.0	24.92	18.0	10.80	3.0	16.0	24.0	31.0	—
IC59—3605—G4 (MF)	36	1.778	35.0	30.226	20.4	13.20	6.0	22.5	26.4	33.4	—
IC59—4206—G4 (MF)	42	1.778	39.5	35.56	23.5	16.54	10.0	20.0	29.0	36.0	○
IC59—4806—G4 (MF)	48	1.778	45.0	40.894	23.5	16.54	10.0	25.0	29.0	36.0	○
IC59—5406—G4 (MF)	54	1.778	50.5	46.228	23.5	16.54	10.0	30.0	29.0	36.0	○
IC59—64075—G4 (MF)	64	1.778	60.0	55.118	27.5	20.32	11.5	40.0	33.5	40.5	○

Unit = mm

(Note) IC59—3605 has a leg srtaightening slot.